



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SMT power inductors

Size 12.5 × 12.5 × 8.5 (mm)

Series/Type: **B82477P4**

Date: **June 2012**

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SMD
Rated inductance 0.82 ... 1000 μ H
Rated current 0.6 ... 11 A
Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding soldered to terminals
- Injection molded base


Features

- High mechanical stability
- High rated current, low DC resistance
- Temperature range up to +150 °C
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics

Terminals

- Base material
Cu ($L \leq 10 \mu\text{H}$), CuSn6P ($L \geq 15 \mu\text{H}$)
- Layer composition Ni, Sn (lead-free)
- Electro-plated

Marking

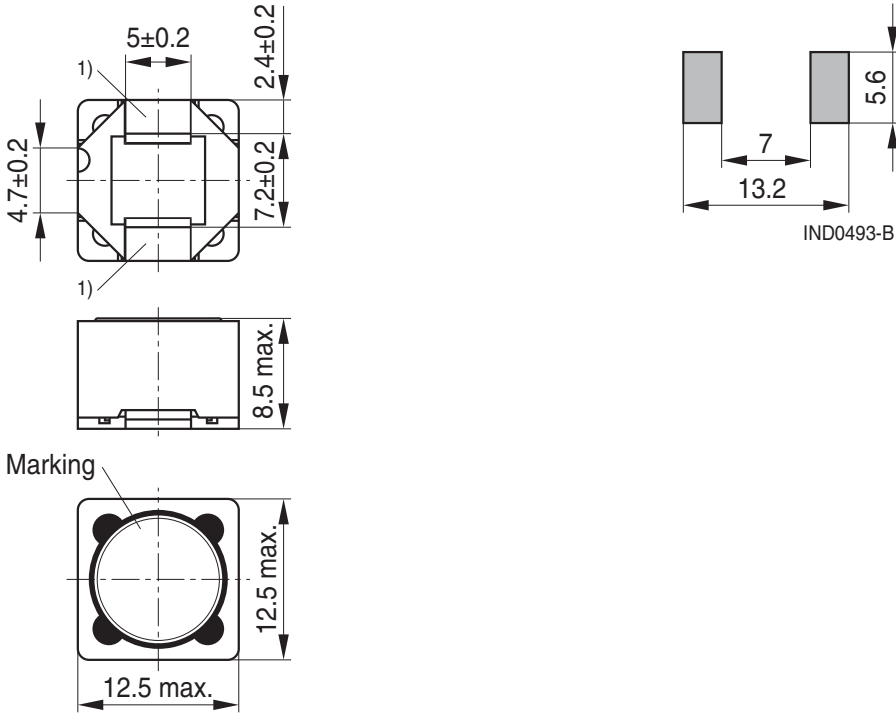
- Marking on component:
Manufacturer, L value (μH , coded),
manufacturing date (YWWD)
- Minimum data on reel:
Manufacturer, ordering code, L value,
quantity, date of packing

Delivery mode and packing unit

- 24-mm blister tape, wound on 330-mm \varnothing reel
- Packing unit: 350 pcs./reel

SMD

Dimensional drawing and layout recommendation



1) Soldering area

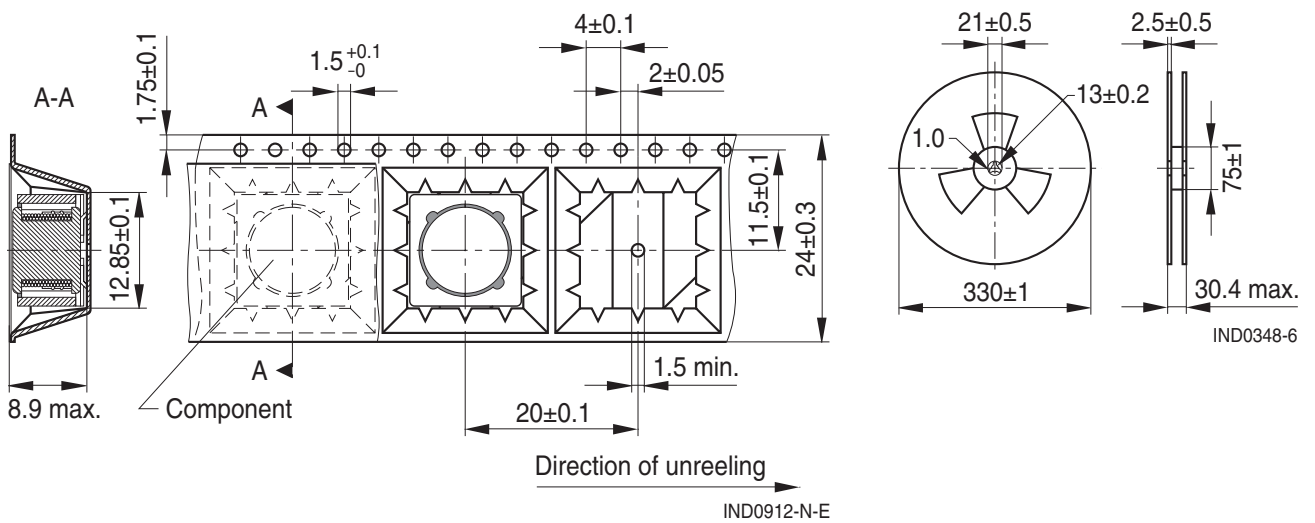
IND0572-K-E

Dimensions in mm

Taping and packing

Blister tape

Reel



Dimensions in mm

SMD
Technical data and measuring conditions

Rated inductance L_R	Measured with LCR meter Agilent 4284A at frequency f_L 0.1 V, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Max. permissible DC with temperature increase of ≤ 40 K at rated temperature
Saturation current I_{sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%
DC resistance R_{max}	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (5 ±0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 4 g

SMD
Characteristics and ordering codes

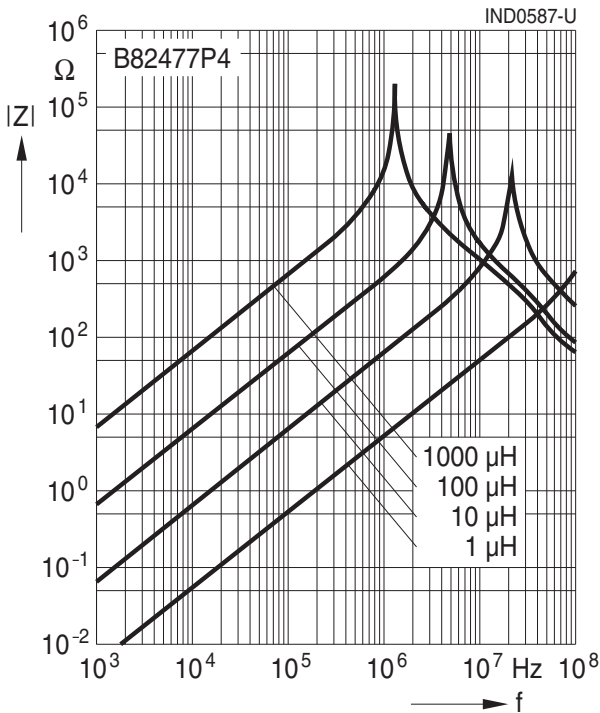
L_R μH	Tolerance	f_L MHz	I_R A	I_{sat} A	R_{max} Ω	Ordering code
0.82	$\pm 20\% \triangleq M$	0.1	11.00	15.00	0.0055	B82477P4821M000
2.0		0.1	8.90	11.00	0.0080	B82477P4202M000
3.3		0.1	8.10	9.60	0.0100	B82477P4332M000
3.9		0.1	8.00	9.50	0.0100	B82477P4392M000
4.7		0.1	7.30	8.40	0.0120	B82477P4472M000
5.6		0.1	7.15	8.30	0.0125	B82477P4562M000
6.8		0.1	6.60	7.30	0.0150	B82477P4682M000
10		0.1	5.80	6.40	0.0190	B82477P4103M000
15		0.1	4.80	5.20	0.0285	B82477P4153M000
22		0.1	4.15	4.35	0.035	B82477P4223M000
33		0.1	3.35	3.50	0.052	B82477P4333M000
47		0.1	2.80	3.00	0.067	B82477P4473M000
68		0.1	2.35	2.45	0.098	B82477P4683M000
82		0.1	2.10	2.25	0.120	B82477P4823M000
100		0.1	1.87	1.95	0.138	B82477P4104M000
150		0.1	1.61	1.70	0.185	B82477P4154M000
220		0.1	1.24	1.35	0.305	B82477P4224M000
330		0.1	1.02	1.15	0.460	B82477P4334M000
470		0.1	0.86	0.95	0.640	B82477P4474M000
680		0.1	0.69	0.78	1.05	B82477P4684M000
1000	0.1	0.60	0.65	1.38	B82477P4105M000	

Version with height 4.8 mm on request (same footprint). Type: B82477P1

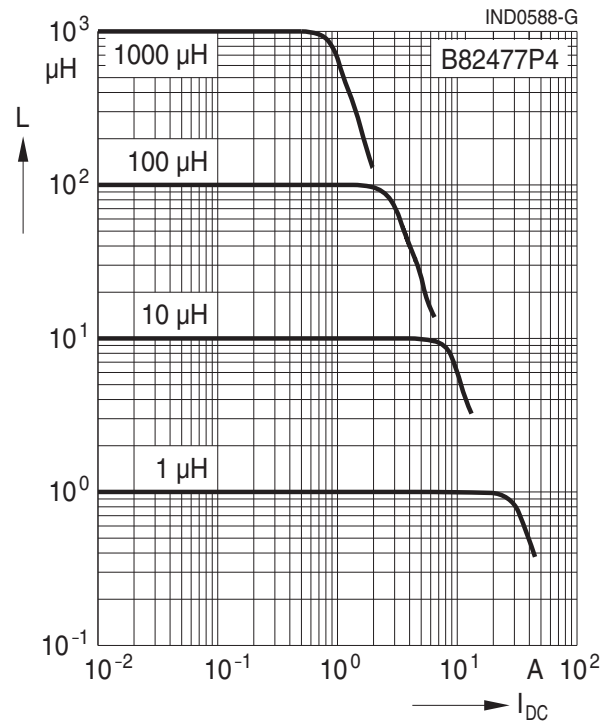
Version with height 6.5 mm on request (same footprint). Type: B82477P2.

SMD

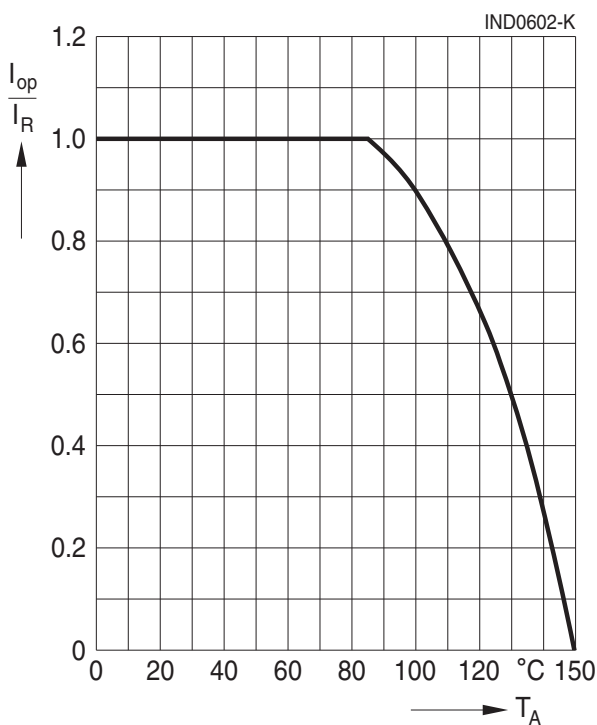
Impedance $|Z|$ versus frequency f
measured with impedance analyzer
Agilent 4294A, typical values at +20 °C



Inductance L versus DC load current I_{DC}
measured with LCR meter Agilent 4275A,
typical values at +20 °C



Current derating I_{op}/I_R
versus ambient temperature T_A
(rated temperature $T_R = +85$ °C)



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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